CLAIMS

1. A machinery (1) for testing one or more electronic components (**DUTs**) at a predetermined thermal condition (**T**), the machinery comprising:

- A surface (4);
- At least one test recess (25) obtained in a part of said surface (4) and into which the component under test can be arranged;
- Means (27, 28a, 28b, 200) for generating the predetermined thermal condition within said test recess (25);
- Said test recess (25) being thermally insulated from a surrounding environment;
- wherein a pre-conditioning recess (20) is obtained on said surface (4) configured for keeping a predetermined temperature condition suitable for conditioning the components under test and wherein said test recess (25) is obtained at a base of the pre-conditioning recess (20);
- wherein said test recess (25) has an upper opening for enabling the insertion of the component under test and wherein a barrier element, arranged in such a way as to be above the component under test and suitable to prevent and/or reduce a thermal dispersion through said upper opening, is comprised;
- wherein said barrier element is in form of a laminar gaseous flow (**f1**) arranged above the component under test and forming a closure for the said upper opening;
- wherein a plurality of nozzles (28a, 28b), arranged at a predetermined height and through which said laminar flow is generated, is comprised and wherein on said surface (4) handling means (5) are arranged for handling

the electronic components under test;

- wherein a storage place (7) for the components under test is further provided;

- Said handling means and said storage place (7) being outside the test recess (25).

2. The machinery, according to claim 1, wherein said means for generating the predetermined thermal condition within the test recess (25) comprise at least one duct (27) arranged within a wall (30, 31) delimiting said test recess and suitable for enabling the circulation of a fluid at a predetermined temperature.

3. The machinery, according to claim 2, comprising a device

(200) suitable for heating and/or cooling said fluid at a required temperature and sending it along said duct, preferably said fluid being a liquid.

4. The machinery, according to one or more of the preceding claims, wherein said means for generating the predetermined thermal condition within the test recess (25) comprise a gas flow (**f2**) at a predetermined temperature and injected within said chamber through one or more injecting nozzles (29a, 29b).

5. The machinery, according to claim 4, wherein said gas flow is air.

6. The machinery, according to one or more of the preceding claims, wherein said test recess (25) is delimited by lateral walls, by the said upper opening, through which the component under test can be inserted within it and by a base equipped with an arrangement place (26) onto which the component under test can be arranged.

7. The machinery (1), according to claim 6, further comprising a housing (11) for a testing device (100), said housing being arranged so that, when said testing device (100) is housed within said housing (11), a part (101) of said testing device (100), provided with electric contacts for carrying out the test, is arranged at said arrangement place (26).

8. The machinery, according to claim 1, wherein said laminar gaseous flow is at room temperature.

9. The machinery, according to claim 1 or 8, wherein said laminar gaseous flow is air.

10. The machinery, according to claim 1, wherein said laminar flow is selectively activatable/deactivatable.

11. The machinery, according to claim 1, wherein said handling means comprise at least one robotic arm (5).

12. The machinery, according to one or more of the preceding claims, wherein a cover (3), of removable type, suitable for covering said surface (4) is provided.

13. A method for carrying out a temperature-dependent test on one or more electronic components under test, the method comprising the following steps:

- Arranging a machinery accordingly to one or more of the previous claims;
- The method providing the generation of a predetermined thermal condition within said test recess and the arrangement of the component under test within the test recess (25);
- wherein the said test recess has the upper opening for enabling the insertion of the electronic component to be tested and the step of arrangement of the barrier element to cover above and thermally insulate said test recess is provided, said barrier element being arranged above the component under test;
- wherein said arrangement of the barrier element provides the generation of the laminar gaseous flow arranged above the component under test so that to close said upper opening.